

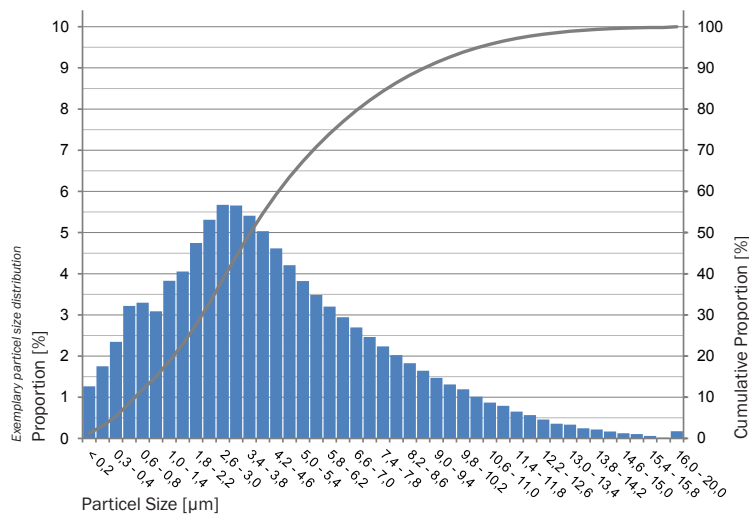


**HeBoFill® 230** is a Boron Nitride powder exhibiting a defined platelet structure and high purity. Virtually no formation of agglomerates. As a filler and additive it improves the temperature resistance and the thermal conductivity.

- Advantages**
- ▶ Optimum lubricating and release properties, also at high temperatures
  - ▶ Electrically insulating
  - ▶ Low formation of agglomerates
  - ▶ Physiologically safe

- Typical Applications**
- ▶ Filler in lubricants and release agents
  - ▶ Filler for polymers

- Technical Values**
- ▶ Colour: White
  - ▶ Boron Nitride: > 98.5 %
  - ▶ Total Oxygen: < 1.0 %
  - ▶ Boron Oxide: < 0.1 %
  - ▶ Carbon: < 0.1 %
  - ▶ Specific Surface Area (BET): ~ 15 m<sup>2</sup>/g
  - ▶ Median Particle Size (D<sub>50</sub>): 3 µm



- Packing Units**
- ▶ 1 kg and 5 kg in plastic bags
  - ▶ 20 kg in compressed fibre drums

**Storage and Safety** Keep dry. Minimum storage life 12 months in original packaging. For further information, please refer to safety data sheet.